

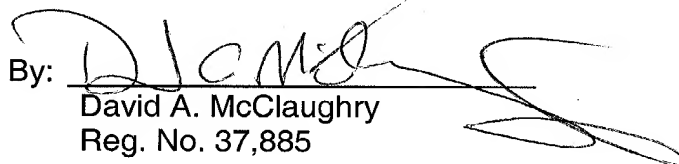
REMARKS

Independent claims 1, 9, 11, and 17 are amended to call for a plurality of spaces. Dependent claims 2, 3, 5, 6, 13, 15, and 16 are amended to conform with their respective base claims. New claims 18-24 are added. If necessary, these new claims should be categorized in Group I.

If the Examiner believes that personal communication will expedite prosecution of this application, the Examiner is invited to telephone the undersigned at (248) 641-1600.

Respectfully submitted,

Dated: April 8, 2002

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ATTACHMENT FOR CLAIM AMENDMENTS

The following is a marked up version of each amended claim in which underlines indicates insertions and brackets indicate deletions.

1. (Amended) A semiconductor device connecting structure for connecting a semiconductor device onto a substrate, characterized by comprising a bonding layer interposed between said semiconductor device and said substrate to accomplish adhesion therebetween, which includes a bonding material for adhering said semiconductor device onto said substrate and a plurality of spaces [space] formed within said bonding material.

2. (Amended) A semiconductor device connecting structure as defined in claim 1, characterized in that said semiconductor device includes a plurality of bumps arranged in rows, and that said plurality of spaces are [space is] formed between said bump rows, outside said bump rows and between said bumps, or at least within at least one of the areas therein.

3. (Twice Amended) A semiconductor device connecting structure as defined in claim 1, characterized in that said [space further comprises a] plurality of spaces are placed closely to each other.

5. (Twice Amended) A semiconductor device connecting structure as defined in claim 1, characterized in that the percentage of said plurality of spaces [space] within said bonding material is 5% to 70%.

6. (Twice Amended) A semiconductor device connecting structure as defined in claim 5, characterized in that the percentage of said plurality of spaces [space] within said bonding material is 10% to 30%.

9. (Amended) A semiconductor device connecting method for connecting a semiconductor device onto a substrate, characterized by comprising the steps of:

interposing a bonding layer between said semiconductor device and said substrate to accomplish adhesion therebetween;

joining said substrate and said semiconductor device to each other by pressing a pressurizing head, heated up to a high temperature, against said semiconductor device to pressurize and heat said bonding layer; and

forming a plurality of spaces [space] within said bonding layer.

11. (Amended) A liquid crystal display unit comprising:

a pair of liquid crystal holding substrates disposed in an opposed relation to each other with liquid crystal therebetween;

a semiconductor device connected onto at least one of said liquid crystal holding substrate; and

a bonding layer interposed between said liquid crystal holding substrate and said semiconductor device to accomplish adhesion therebetween, characterized in that

said bonding layer includes a bonding material for adhering said semiconductor device onto said liquid crystal holding substrate and a plurality of spacers [space] formed within said bonding material.

13. (Twice Amended) A liquid crystal display unit as defined in claim 11, characterized in that said [space further comprises a] plurality of spaces are placed closely to each other.

15. (Twice Amended) A liquid crystal display unit as defined in claim 11, characterized in that the percentage of said plurality of spaces [space] within said bonding material is 5% to 70%.

16. (Twice Amended) A liquid crystal display unit as defined in claim 15, characterized in that the percentage of said plurality of spaces [space] within said bonding material is 10% to 30%.

17. (Amended) An electronic apparatus having a plurality of semiconductor driving output terminals and a liquid crystal display unit connected to said semiconductor driving output terminals, characterized in that said liquid crystal display unit includes:

a pair of liquid crystal holding substrates disposed in an opposed relation to each other with liquid crystal therebetween;

a semiconductor device connected onto at least one of said liquid crystal holding substrates; and

a bonding layer interposed between said liquid crystal holding substrate and said semiconductor device to accomplish adhesion therebetween,

wherein said bonding layer includes a bonding material for adhering said semiconductor device onto said liquid crystal holding substrate and a plurality of spaces [space] formed within said bonding material.